

View Online at https://aerobasegroup.com/nsn/5910-01-256-2662

Body Style: Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.010 **Terminal Length:** 0.015 inches **Body Length:** 0.110 inches **Body Width:** 0.110 inches **Body Height:** Between 0.030 inches and 0.102 inches **Schematic Diagram Designator:** No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp:

100000.0 megohms

Capacitance Value Per Section:

6.800 picofarads single section

Nonderated Operating Temp:

Between -55.0 degrees celsius and 125.0 degrees celsius

Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:

90.0 single section

Nonderated Continuous Voltage Rating And Type Per Section:

500.0 dc single section

Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:

-20.0/+20.0 single section

Tolerance Range Per Section:

-0.10/+0.10 picofarads single section

Case Material:

Ceramic or glass

Insulation Resistance At Reference Temp:

1000000.0 megohms

Dissipation Factor At Reference Tempurature In Percent:

0.050

Quality Factor At Reference Temp:

1000.000

Terminal Surface Treatment:

Palladium and silver

Precious Material And Location:

Terminal surfaces palladium and terminal surfaces silver



Test Data Document:

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).
Terminal Type And Quantity:
2 bonding pad
Specification Data:
81349-mil-c-55681/4 government specification
Shelf Life:
N/a
Unit Of Measure:
-Demilitarization:
No
Fig:
A010b0